

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4337321	conditioner conditioning conditions condition conditioners	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:52
L2	824861	friction	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:52
L3	12009	polishing adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:52
L4	75	I1 with I2 with I3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:52
L5	4417637	detect detects detected detecting detector detectors sensor sensors sense sensed senses sensing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:53
L6	20	I4 with I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:59
L7	2	"5456627".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:56
L8	7662	I2 near5 I5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 12:59

L9	30	I1 same I3 same I8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:12
L10	46	(I1 with I3) and I8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:12
L11	29979	moore.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:12
L12	33	I10 not I11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:13
L13	804585	belt belts	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:29
L14	1881542	continuous	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:29
L15	2497616	I13 I14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:29
L16	749	linear with polishing with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:30

L17	241	L15 with L16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 13:30
L18	2	"1594445".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:34
L19	2	"2671993".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:34
L20	1	"4347689".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:35
L21	1	"4443977".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:35
L22	1	"4642943".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:35
L23	1	"5065547".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:35
L24	1	"5088240".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:36
L25	1	"5099615".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:36
L26	1	"5209027".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:36
L27	1	"5276999".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:36
L28	1	"5335453".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:36
L29	1	"5399125".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:36
L30	1	"5476413".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:37
L31	1	"5490808".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:37
L32	1	"5558568".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:37
L33	1	"5593344".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:37
L34	1	"5692947".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:37
L35	1	"5722877".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:38
L36	1	"5762536".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:38
L37	1	"5762536".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:38

L38	1	"5800248".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:38
L39	1	"5871390".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:38
L40	1	"5899794".PN.	USPAT; USOCR	OR	OFF	2005/02/18 13:39
S1	4	"5833519".PN. OR "5904608".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 06:55
S2	2899172	wafer wafers semiconductor semiconductors substrate substrates	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 06:55
S3	4357122	condition conditioner conditioning conditions conditioners conditioned	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 06:56
S4	824861	friction (friction adj force)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 06:56
S5	4357122	S3 S3 with S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 06:56
S6	34676	S3 with S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 06:59
S7	531	S2 same S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 07:00

S8	186199	polishing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 07:00
S9	152	S7 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 07:00
S10	97533	"451"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 07:00
S11	72	S9 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 07:00
S12	749	linear with polishing with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:57
S13	700	S12 and (cmp (chemical adj mechanical adj polishing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:57
S14	4357122	condition conditioner conditioning conditions conditioners conditioned	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:49
S15	502	S13 and S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:58

S16	502	S15 and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:50
S17	824861	friction (friction adj force)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:50
S18	187	S15 and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:58
S19	156	S18 and "451"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:56
S20	14	S12 with vertical	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:56
S21	632	vertical with polishing with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:57
S22	499	S21 and (cmp (chemical adj mechanical adj polishing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:57
S23	403	S22 and S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 10:58

S24	118	S23 and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 11:15
S25	2	"6179689".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 11:17
S26	2	"6273796".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/18 11:17